

10/075566
02/13/02

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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10075566	FILING DATE 02/13/2002	CLASS 134	SUBCLASS 003	GAU 1746	EXAMINER CHAUDHRY
**APPLICANTS: Aoki Hidemitsu; Yamasaki Shinya;					
<h1>BEST AVAILABLE COPY</h1>					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A DIV OF 09/313,027 05/17/1999					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 10-138365 05/20/1998					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials		ATTORNEY DOCKET NO 12688A			
TITLE : Method for cleaning semiconductor wafer after chemical mechanical polishing on copper wiring					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims _____ Print Claim for O.G. _____	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg. _____ Print Fig. _____
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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